

Millimeter-wave load-pull techniques

Original

Millimeter-wave load-pull techniques / Teppati, Valeria. - (2014). (Intervento presentato al convegno IEEE International Microwave Symposium tenutosi a Tampa (FL) nel June 2014).

Availability:

This version is available at: 11583/2536696 since:

Publisher:

IEEE / Institute of Electrical and Electronics Engineers Incorporated:445 Hoes Lane:Piscataway, NJ 08854:

Published

DOI:

Terms of use:

This article is made available under terms and conditions as specified in the corresponding bibliographic description in the repository

Publisher copyright

(Article begins on next page)



Millimeter-wave load-pull techniques

Valeria Teppati
ETH Zürich

This work was supported in part by the Swiss National Science Foundation (SNSF) under Grant R'Equip 206021_144952/1 and Grant PMPDP2_139697 and by ETH Zürich under Scientific Equipment Program 03721

International Microwave Symposium
IEEE 1-6 June 2014, Tampa Bay, FL MTT-S

Outline

- ▶ Introduction
 - ▶ Basics of large signal characterization
 - ▶ Applications
- ▶ Large Signal Characterization at high frequency
 - ▶ Existing solution examples
 - ▶ Pros and cons
- ▶ A W-band on-wafer load-pull system
 - ▶ Block scheme
 - ▶ Calibration and accuracy verification
- ▶ Measurement examples
- ▶ Conclusions

Introduction

Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples

International Microwave Symposium
1-6 June 2014, Tampa Bay, FL

Large signal Characterization

Basics	Applications
<ul style="list-style-type: none"> ▶ Linear characterization (small signal) provides full information as long as the device under test (DUT) can be considered linear <ul style="list-style-type: none"> ▶ e.g. passive components, transmission lines ▶ Active devices show nonlinear behavior when excited in realistic (large signal) conditions 	<ul style="list-style-type: none"> ▶ Many applications require measuring a few device performances in CW, while exciting its nonlinearities ▶ Examples: <ul style="list-style-type: none"> ▶ Performance/technology evaluation ▶ Circuit design ▶ Large signal models refinement
<ul style="list-style-type: none"> ▶ The extension of S-parameters to X-parameters might be too complicated ▶ What information do we really need? 	<ul style="list-style-type: none"> ▶ Reliability/failure tests ▶ Production tests

Basics of Large signal Characterization

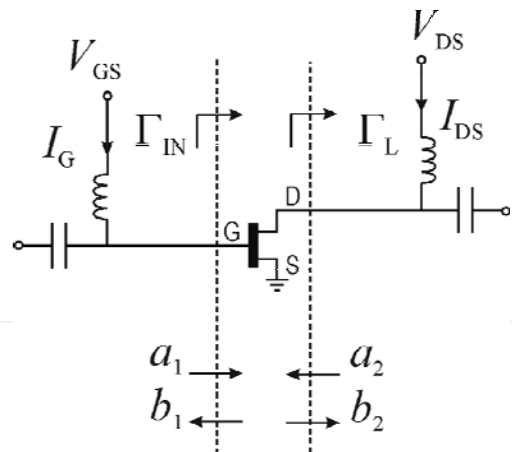
- ▶ We focus on the simplest example: a two port active device (a transistor in common source configuration) fed with a single CW tone @ f_0

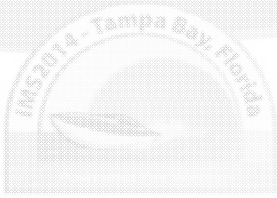
- ▶ Interesting performances:

- ▶ DC power, $P_{DC} = V_{GS} I_G + V_{DS} I_D$
- ▶ Output power: $P_{OUT} = |b_2|^2 - |a_2|^2 @ f_0, 2f_0, \dots, nf_0$
- ▶ Gain = $P_{OUT} / P_{IN} @ f_0$
- ▶ Power added efficiency, $PAE = (P_{OUT} - P_{IN}) / P_{DC} @ f_0$

- ▶ Influence parameters:

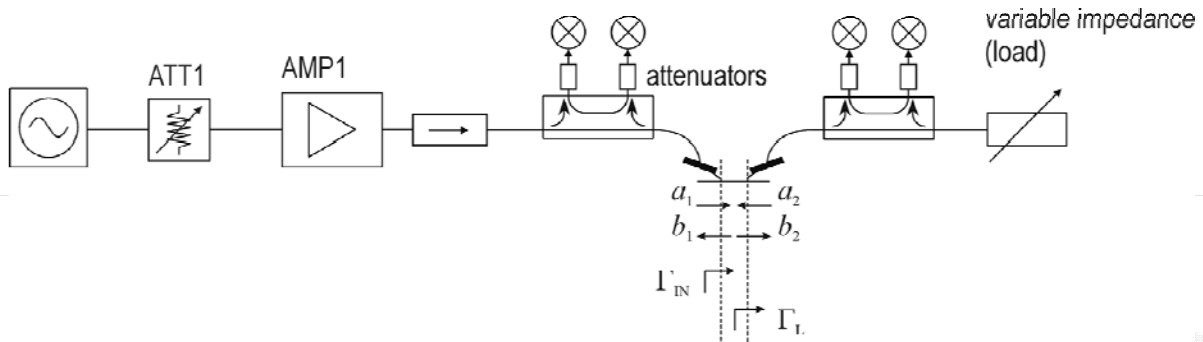
- ▶ Bias point (DC supply)
- ▶ Frequency f_0
- ▶ Input power: $P_{IN} = |a_1|^2 - |b_1|^2$
- ▶ $\Gamma_L = a_2 / b_2 @ f_0, 2f_0, \dots, nf_0$





Load-pull measurements

- ▶ A simplified block scheme of an **on-wafer** load-pull measurement system
- ▶ On-wafer "environment" adds complications
 - ▶ calibration
 - ▶ additional losses

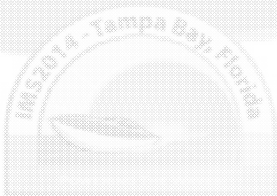


Introduction

Large signal
characterization

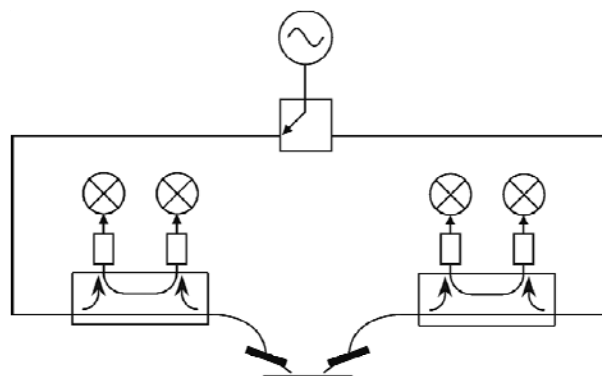
A W-band on-wafer
load-pull system

Measurement
examples



Load-pull calibration – vector calibration

- ▶ Vector "VNA-like" calibration



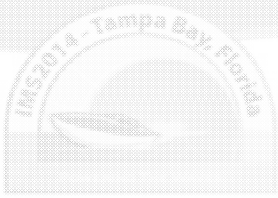
On-wafer or
calibration substrate
standards

Introduction

Large signal
characterization

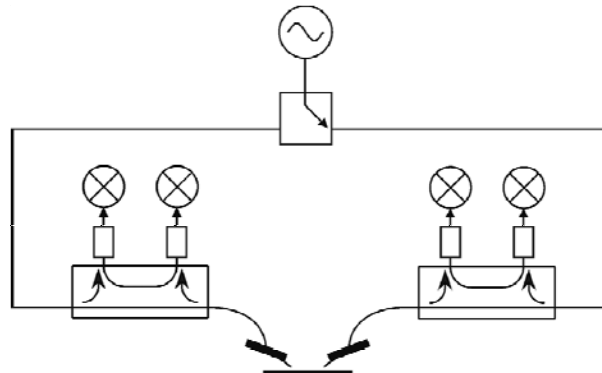
A W-band on-wafer
load-pull system

Measurement
examples



Load-pull calibration – vector calibration

- ▶ Vector “VNA-like” calibration



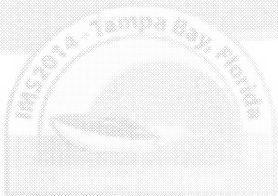
On-wafer or
calibration substrate
standards

Introduction

Large signal
characterization

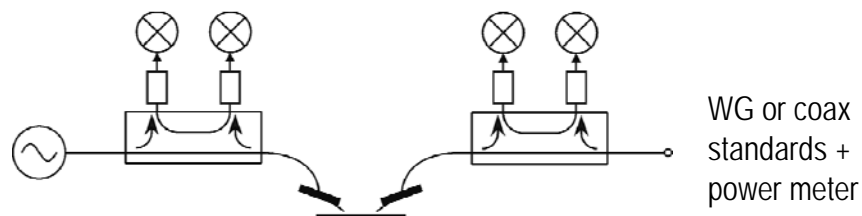
A W-band on-wafer
load-pull system

Measurement
examples



Load-pull calibration – power calibration

- ▶ Power calibration



On-wafer or
calibration substrate
thru

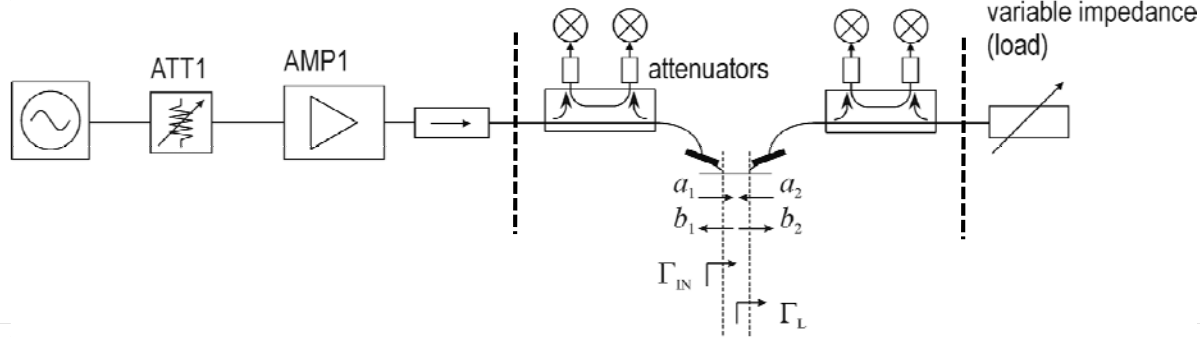
Introduction

Large signal
characterization

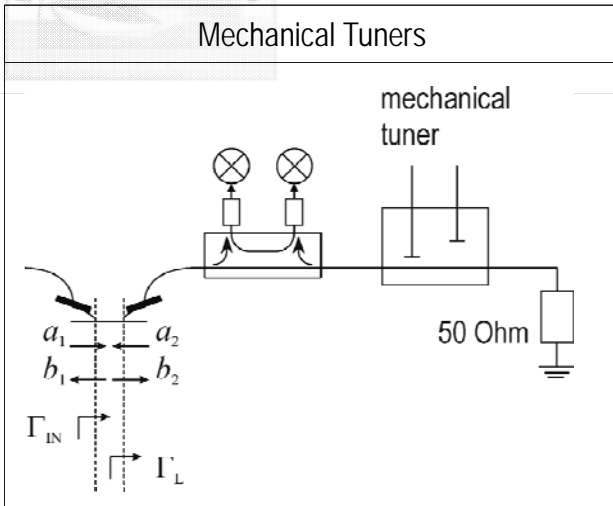
A W-band on-wafer
load-pull system

Measurement
examples

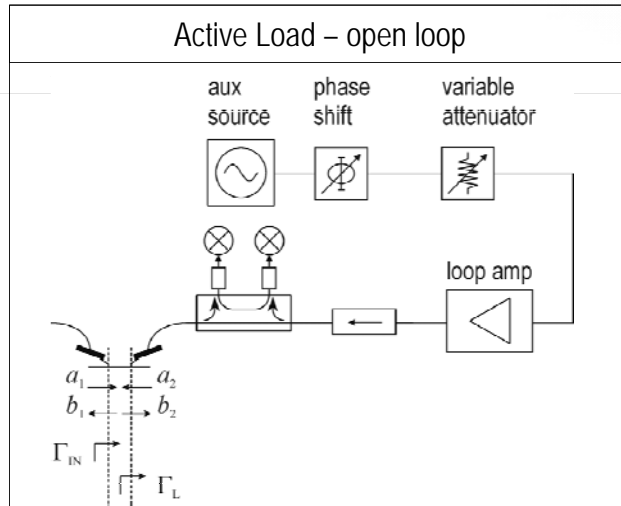
- ▶ After calibration it is possible to modify the set up at the right of reflectometer 2 and at the left of reflectometer 1, without affecting calibration



Solutions for tunable loads



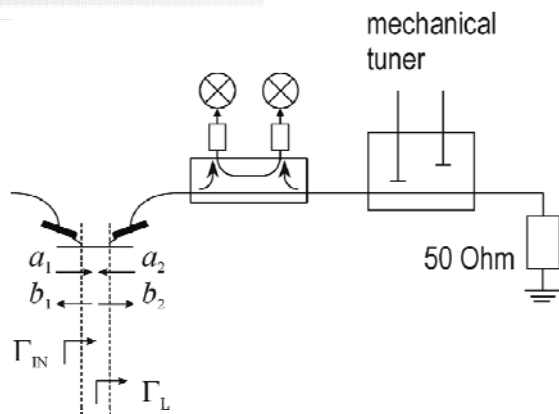
- ▶ Main issue: gamma limitation
 - ▶ Losses cannot be compensated
 - ▶ 2.5 dB losses reduce $|\Gamma|=1$ to $|\Gamma|=0.56$
 - ▶ 0.2 dB losses reduce $|\Gamma|=1$ to $|\Gamma|=0.95$



- ▶ Main issue: gamma varies with P_{OUT}
 - ▶ Compensated by iterations

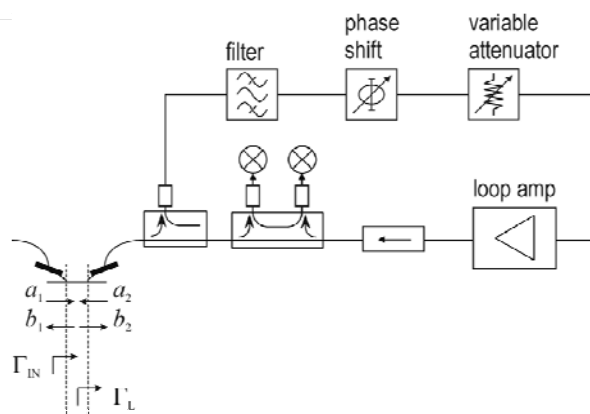
Solutions for tunable loads

Mechanical Tuners



- ▶ Main issue: gamma limitation
 - ▶ Losses cannot be compensated
 - ▶ 2.5 dB losses reduce $|\Gamma|=1$ to $|\Gamma|=0.56$
 - ▶ 0.2 dB losses reduce $|\Gamma|=1$ to $|\Gamma|=0.95$

Active Load – closed loop



- ▶ Main issue: possible oscillations
 - ▶ Reduced risk when losses are reduced

Introduction

Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples

Load-pull measurements above 60 GHz

Mechanical Tuners

- ▶ Mechanical tuners exist (sold by main vendors) in the millimeter-wave range, up to 110 GHz
 - ▶ require pre-calibration
 - ▶ Including probe and set-up losses, 0.5-0.6 gamma is reachable on-wafer

References

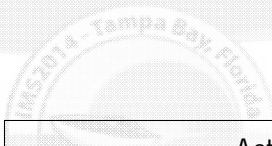
- ▶ E. Alekseev, D. Pavlidis, and C. Tsironis, "W-band on-wafer load-pull measurement system and its application to HEMT characterization," in IEEE MTT-S, Baltimore, MD, USA, Jun. 1998, pp. 1479–1482.
- ▶ D. W. Baker, et al., "On-wafer load pull characterization of W-band InP HEMT unit cells for CPW MMIC medium power amplifiers," in IEEE MTT-S, Anaheim, CA, USA, Jun. 1999, pp. 1743–1746.
- ▶ L. Boggione and R. T. Webster, "200 GHz f_T SiGe HBT load pull characterization at mmwave frequencies," in IEEE RFIC Symposium, Anaheim, CA, USA, Jun. 2010, pp. 215–218.
- ▶ C. Li et al. "Investigation of loading effect on power performance for planar Gunn diodes using load-pull measurement technique," IEEE MWCL, vol. 21, no. 10, pp. 556–558, Oct. 2011.
- ▶ A. Pottrain, et al., "High power density performances of SiGe HBT from BiCMOS technology at W-band," IEEE Electron Device Letters, vol. 33, no. 2, pp. 182–184, Feb. 2012.

Introduction

Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples



Load-pull measurements above 60 GHz

Active Loads

- ▶ Open loop active loads combined with
 - ▶ 6-port measurements
 - ▶ Mixed signal measurement technique

References

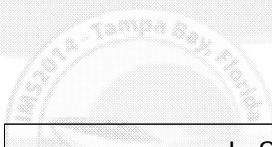
- ▶ S. A. Chahine, B. Huyart, E. Bergeault, and L. P. Jallet, "An active millimeter load-pull measurement system using two six-port reflectometers operating in the W-frequency band," IEEE Trans. Instrum. Meas., vol. IM-51, pp. 408–412, Jun. 2002.
- ▶ L. Galatro, M. Marchetti, M. Spirito, "60 GHz mixed signal active load-pull system for millimeter wave devices characterization," Microwave Measurement Symposium (ARFTG), 2012 80th ARFTG , vol., no., pp.1,6, 29-30 Nov. 2012.

Introduction

Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples



Load-pull measurements above 60 GHz

In Situ Tuners

- ▶ "In-situ" (integrated)
 - ▶ Still gamma limited
 - ▶ Integration required
 - ▶ no real-time

References

- ▶ T. V. Heikkil, J. Varis, J. Tuovinen, and G. M. Rebeiz, "W-band RF MEMS double and triple-stub impedance tuners," in IEEE MTT-S Intl. Microwave Symp. Dig., Long Beach, CA, USA, Jun. 2005, pp. 923–926.
- ▶ Y. Tagro, N. Waldhoff, D. Gloria, S. Boret, G. Dambrine, "In Situ Silicon-Integrated Tuner for Automated On-Wafer MMW Noise Parameters Extraction Using Multi-Impedance Method for Transistor Characterization," IEEE Transactions on Semiconductor Manufacturing, vol.25, no.2, pp.170,177, May 2012
- ▶ T. Quemerai, D. Gloria, S. Jan, N. Derrier, P. Chevalier, "Millimeter-wave characterization of Si/SiGe HBTs noise parameters featuring f_T/f_{MAX} of 310/400 GHz," Radio Frequency Integrated Circuits Symposium (RFIC), 2012 IEEE , vol., no., pp.351,354, 17-19 June 2012

Introduction

Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples



94 GHz on-wafer active-loop load-pull system

- ▶ Mechanical tuners with pre-calibration: less accurate than real-time
 - ▶ Mechanical tuners with real-time measurements: reduced gamma (0.5 maximum is typical)
 - ▶ In situ tuners: integration with the device / highly developed fabrication capabilities
- ↓
- ▶ Active loads with real-time measurements are a good solution, not yet widely diffused

Introduction

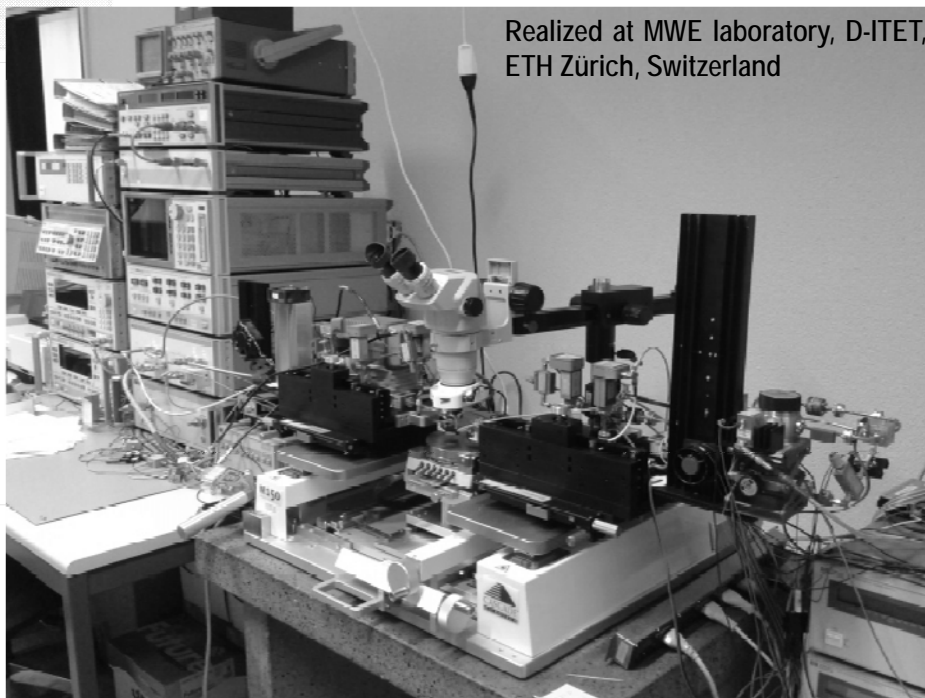
Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples



94 GHz on-wafer active-loop load-pull system



Introduction

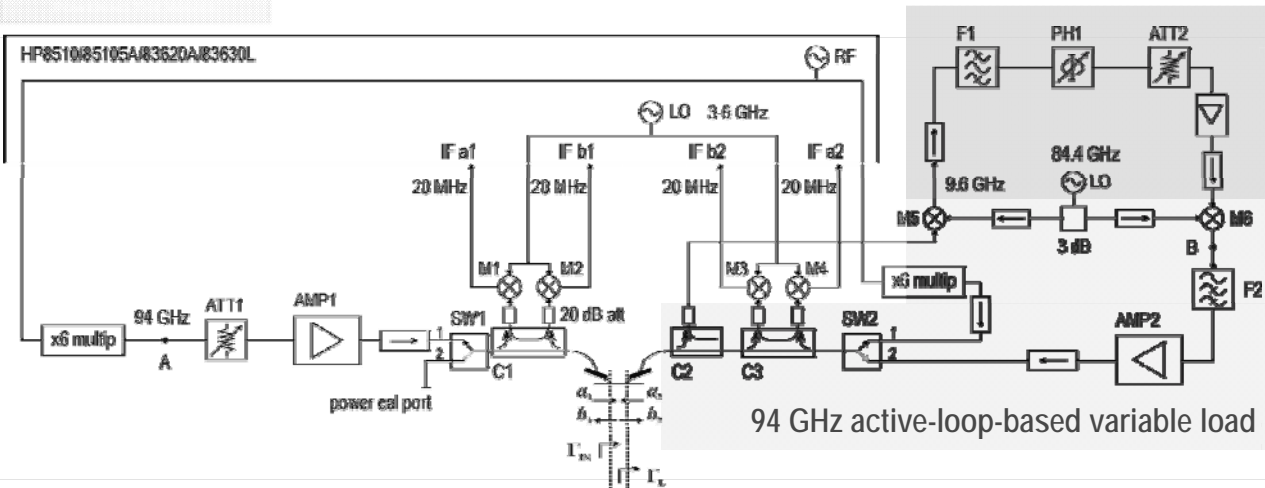
Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples

94 GHz on-wafer active-loop load-pull system

- Simplified block diagram (*)



- Novelty – the *down-conversion-based* active loop
 - Similar techniques exist to realize IF loads, at a few hundreds of MHz

(*) V. Teppati, H.-R. Benedikter, et al., "A W-Band On-Wafer Active Load-Pull System based on Down-Conversion Techniques", IEEE Transactions on Microwave Theory and Techniques, Vo. 64, is.1, Jan. 2014, pp. 148-153.

Introduction

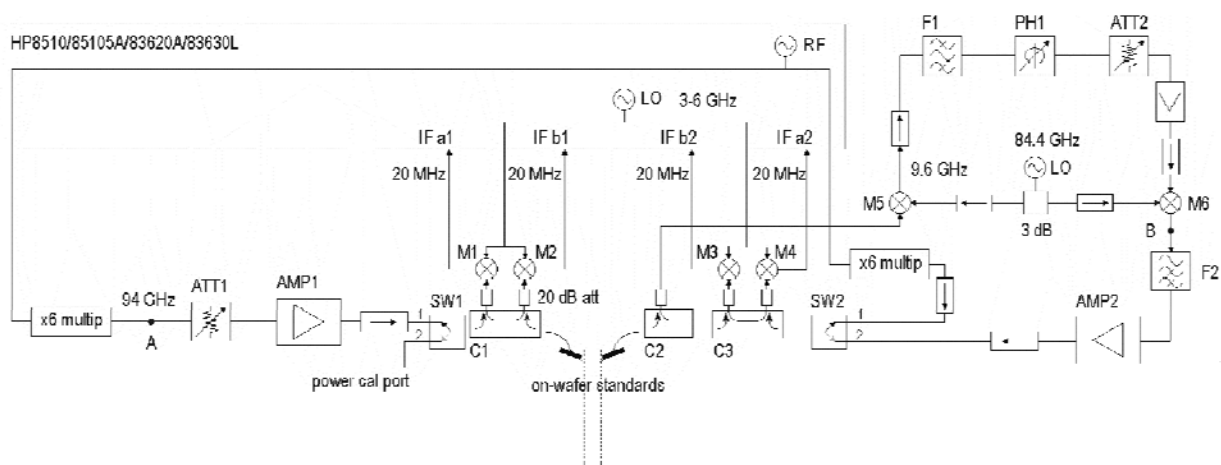
Large signal characterization

A W-band on-wafer load-pull system

Measurement examples

Load-pull system calibration – step 1

- SW1 and SW2 in position 1
- On-wafer (or calibration substrate) standards are connected and measured



Introduction

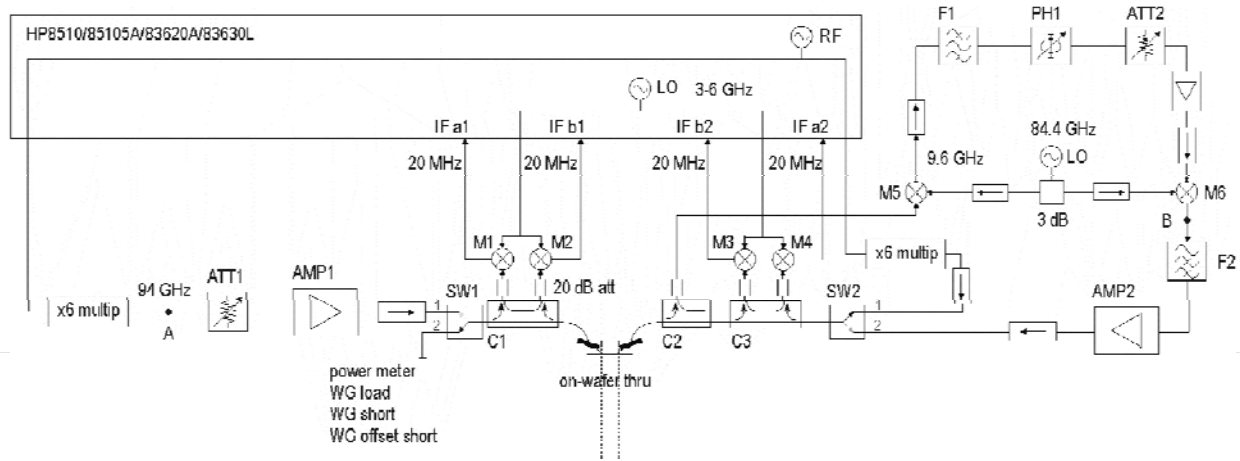
Large signal characterization

A W-band on-wafer load-pull system

Measurement examples

Load-pull system calibration – step 2

- ▶ SW1 in position 2 and SW2 in position 1, thru connection



Introduction

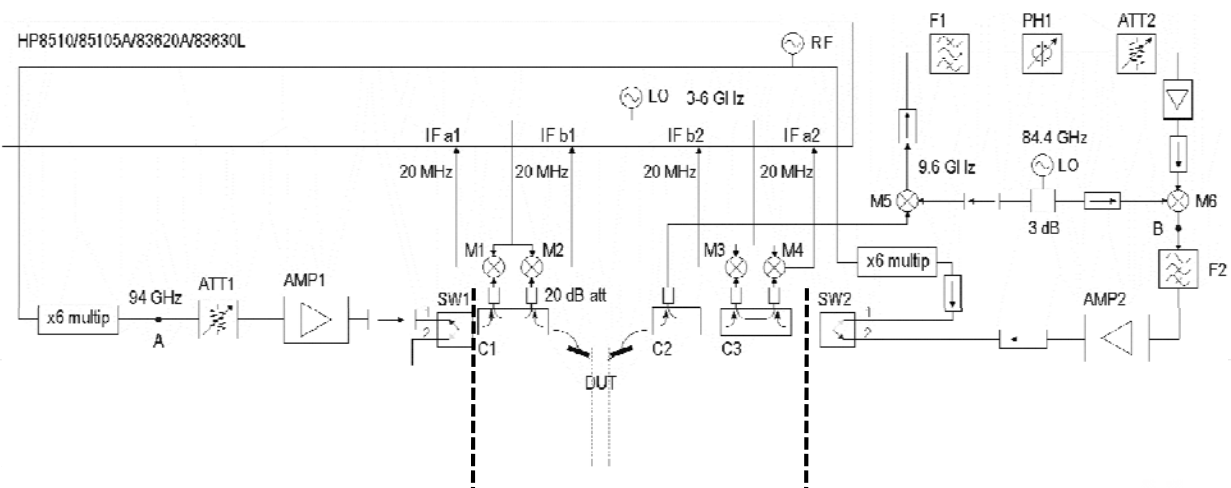
Large signal characterization

A W-band on-wafer load-pull system

Measurement examples

Measurement Phase

- ▶ SW1 in position 1 and SW2 in position 2
- ▶ It is possible to modify the set up (add a circulator, or a spectrum analyzer) at the right of reflectometer 2 and at the left of reflectometer 1, without affecting calibration



Introduction

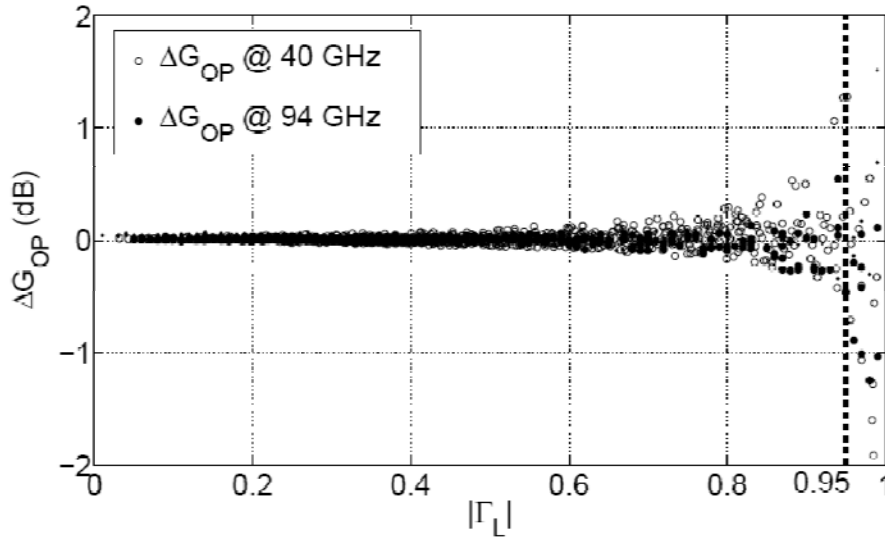
Large signal characterization

A W-band on-wafer load-pull system

Measurement examples

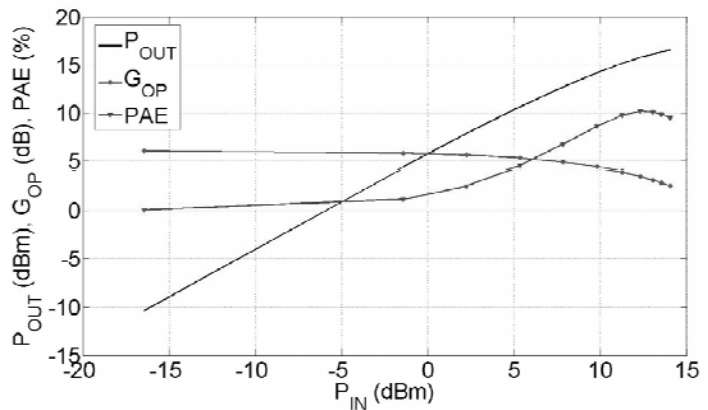
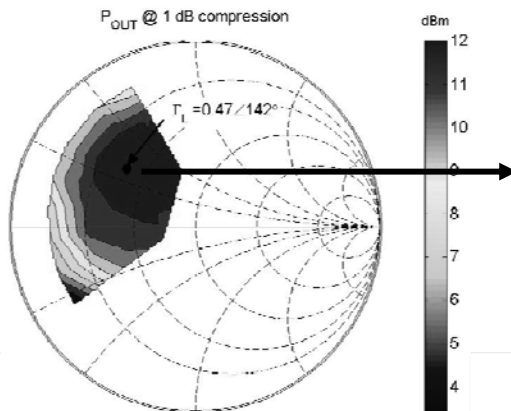
Residual error comparison

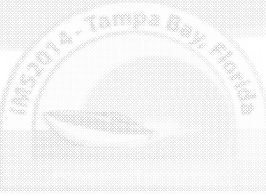
- ▶ A "thru" (on-wafer direct connection) should have 0 dB gain
- ▶ Its gain variation vs. Γ_L is taken as an estimation of the accuracy of the measurement



Measurement examples

- ▶ 0.1x100 μm^2 GaN HEMT
- ▶ $V_{DS}=5\text{ V}$, $V_{GS}=-3\text{ V}$ (class A)

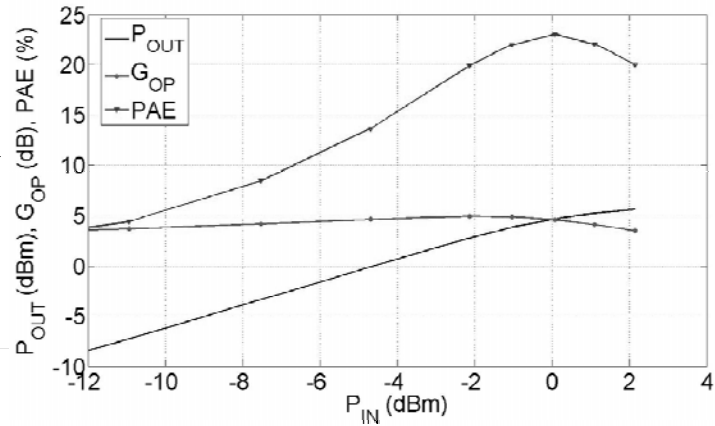
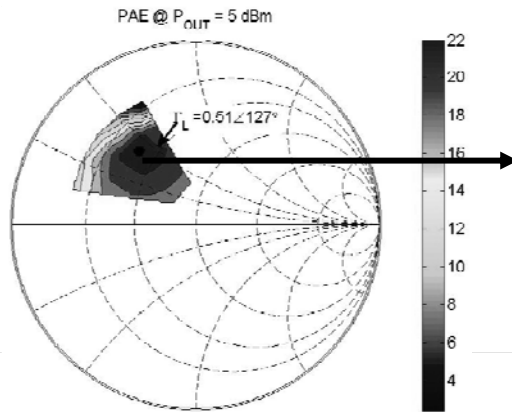




Measurement examples

▶ $0.3 \times 8.4 \mu\text{m}^2$ InP/GaAsSb DHBT

- ▶ $V_{CE} = 1.6 \text{ V}$, $V_{BE} = 0.75 \text{ V}$ (class AB)



Introduction

Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples

▶ Basics of large signal characterization

- ▶ Mechanical tuners vs. active loads

▶ Existing solutions for large signal characterization at high frequencies

▶ W-band, down-conversion active loop, on-wafer load-pull system

- ▶ accuracy
- ▶ measurement examples

Introduction

Large signal
characterization

A W-band on-wafer
load-pull system

Measurement
examples